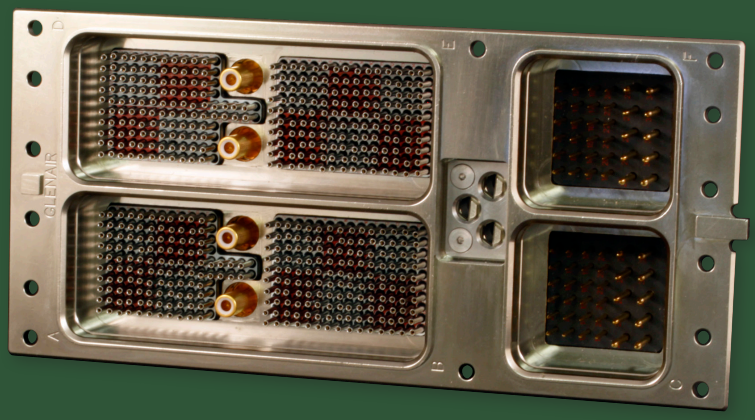
SERIES 28

HiPer-D® vs. ARINC 600

Smaller, lighter HiPer-Ds with robust EMI/grounding performance save weight, and reduce assembly time and complexity compared to conventional ARINC backplane/ motherboard configurations.



Legacy ARINC 600 type solutions are no longer optimized for the size and weight reduction requirements of today's aircraft industry.

High-performance HiPer-D® connectors with their advanced EMI shielding, grounding, environmental sealing, and guide-pin-managed blind mate capabilities allow designers to implement a distributed architecture model with significant performance advantages.

Available HiPer-D® insert arrangements, from 9 – 104 way and supported contact types including size #22 and #20 signal as well as size #8 power and coax.

The opportunity to replace big, bulky and expensive ARINC 600 type rack-and-panel connectors with a distributed architecture utilizing discrete D-subminiature connectors is finally realized with the high-performance Glenair HiPer-D®. With the outstanding performance of the HiPer-D, system designers are now able to optimize available space in equipment consoles and boxes without compromising EMC or temperature tolerances. Distributed interconnect architectures of this type also allow for easier troubleshooting, and the ability to eliminate expensive motherboards and of course, cumbersome rack-and-panel ARINC connectors. The ability to separate out intrinsically safe functions—for example segregating power circuits completely from signal circuits—allows designers to build handier systems which are easier to assemble and maintain.

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